

THERMOELECTRICALLY COOLING ELECTRONIC DEVICES

Abstract of the Disclosure

A heat sink may be clamped to a thermoelectric cooler and vapor chamber using a U-shaped retention band. The band may attach underneath the vapor chamber, extending
5 around the thermoelectric cooler, and over a heat sink. The heat sink may include a plate to distribute the force of the band across the heat sink. Bolts may be utilized to transfer the force from the free ends of the U-shaped retention band to a vapor chamber support frame. Thus, in
10 some embodiments of the present invention, a thermoelectric cooler may be clamped to a heat sink without wasting heat transfer area through the use of bolts, without unnecessary bending, and without requiring a relatively thick base on the heat sink.